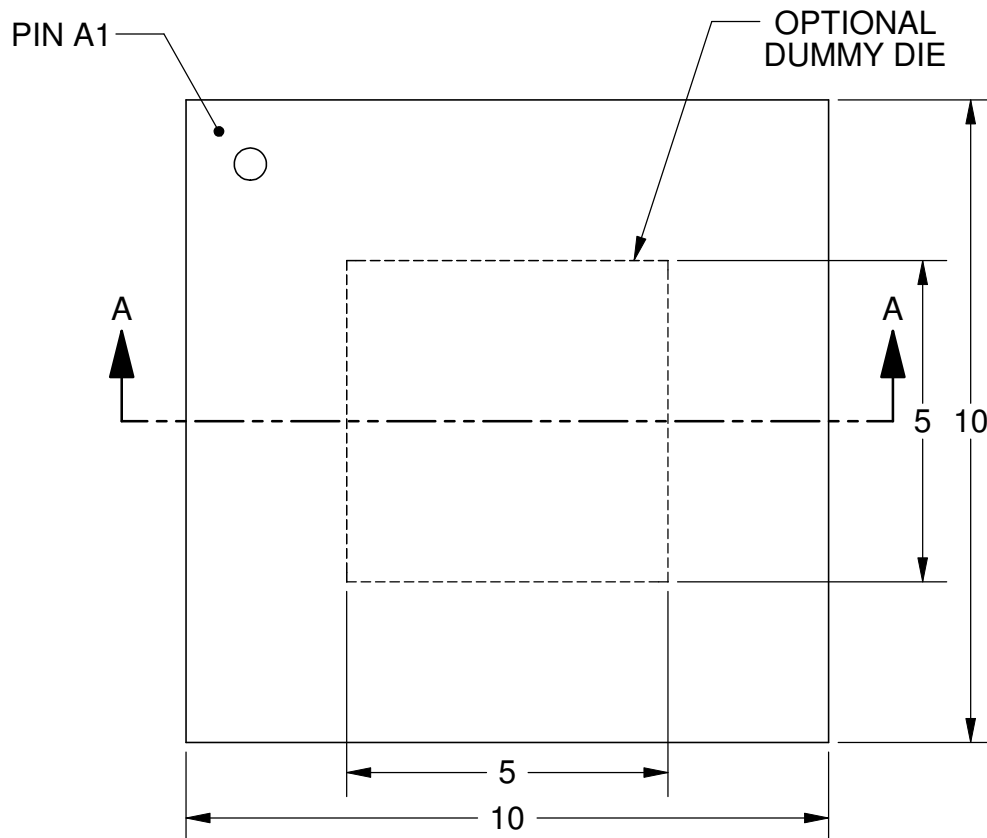
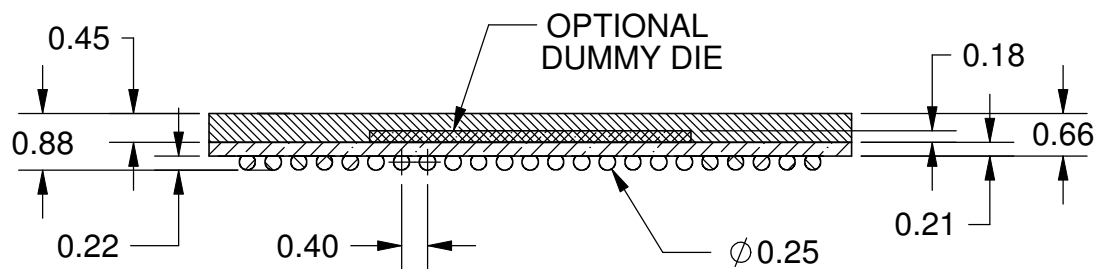
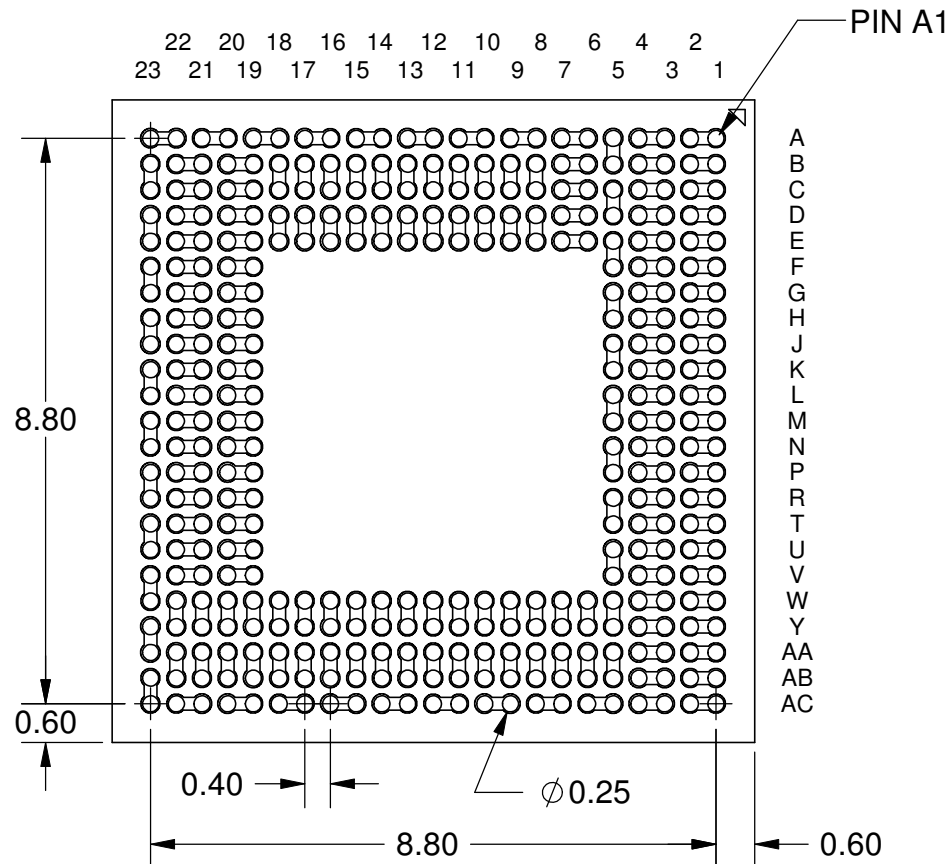


TOP VIEW



BALL VIEW



SECTION A-A

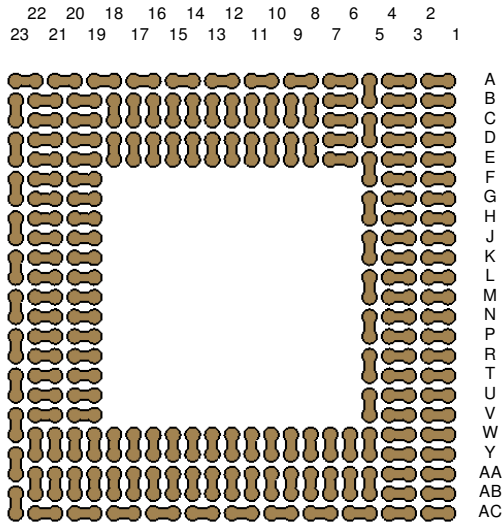
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.20mm.
- 5) PAD Cu DIAMETER: 0.30mm.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

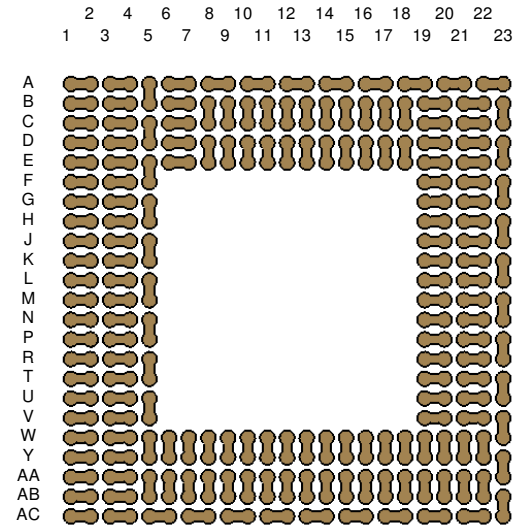
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA360T.4C-DC235	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA360T.4C-DC235D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA360T.4-DC235	Sn63/Pb37	NO	NO	NO
BGA360T.4-DC235D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE		<b>TopLine</b> <sup>®</sup>				
X.X	+/- 0.10	DRAWN J. Hines		6/18/2011						TITLE
X.XX	+/- 0.05	ENG				BGA360T.4C-DC235D				
X.XXX	+/- 0.025	MFG				DAISY CHAIN DUMMY				
ANGLES +/- 0.5°		QA		SCALE		SIZE		DRAWING NO.		REV
ALL DIMENSIONS IN		CUST		8.5:1		A		542353		A
□ INCHES    ☒ MILLIMETERS		REVISED								
THIRD ANGLE PROJECTION										
								DO NOT SCALE DRAWING		SHEET 1 OF 2

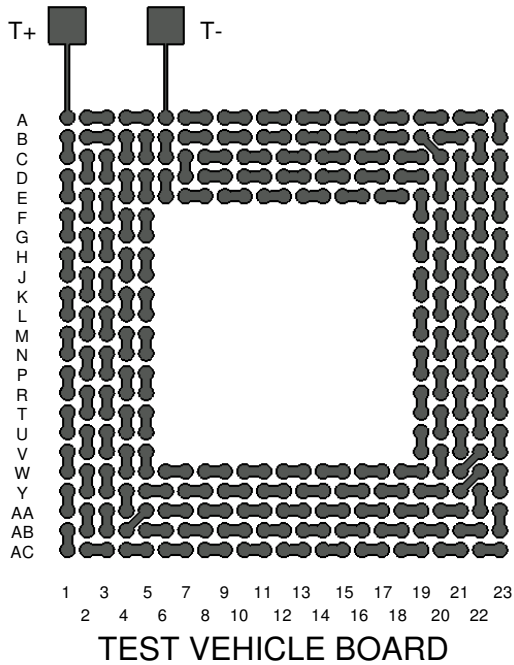
BALL VIEW



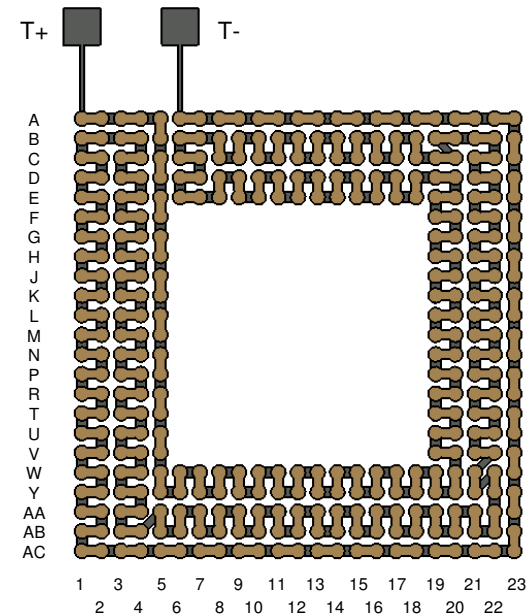
BOTTOM SIDE  
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING  
TO TEST BOARD  
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.30mm (11.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.20mm (7.8mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.20mm (7.8mil).

<b>TopLine</b> ®			
TITLE		BGA360T.4C-DC235D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
6.5:1	A	542353	A
DO NOT SCALE DRAWING			SHEET 2 OF 2

